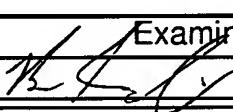
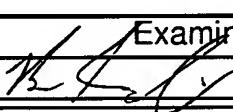
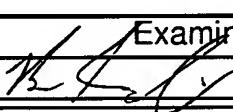


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	OPTIMUM PADSET FOR WIRE BONDING RF TECHNOLOGIES WITH HIGH-Q INDUCTORS																																																																																						
<p>Application Number : Confirmation Number: First Named Applicant: Douglas Coolbaugh Attorney Docket Number: BUR920020119US1 Art Unit: Examiner: Search string: (4845543 or 5139192 or 5773899 or 5884835 or 6027999 or 6027999 or 6077766 or 6218728 or 6306750).pn</p>																																																																																							
<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>BS</td><td>1</td><td>4845543</td><td>1989-07-04</td><td>Okikawa et al</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5139192</td><td>1992-08-18</td><td>Simmonds</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5773899</td><td>1998-06-30</td><td>Zambrano</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5884835</td><td>1999-06-23</td><td>Kajiwara et al</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>6027999</td><td>2000-02-22</td><td>Wong</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>6027999</td><td>2000-02-22</td><td>Wong</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>6077766</td><td>2000-06-20</td><td>Sebesta et al</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>6218728</td><td>2001-04-17</td><td>Kimura</td><td></td><td></td><td></td></tr><tr><td>X</td><td>9</td><td>6306750</td><td>2001-10-23</td><td>Huang et al</td><td></td><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	BS	1	4845543	1989-07-04	Okikawa et al					2	5139192	1992-08-18	Simmonds					3	5773899	1998-06-30	Zambrano					4	5884835	1999-06-23	Kajiwara et al					5	6027999	2000-02-22	Wong					6	6027999	2000-02-22	Wong					7	6077766	2000-06-20	Sebesta et al					8	6218728	2001-04-17	Kimura				X	9	6306750	2001-10-23	Huang et al			
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**LIST OF PRIOR ART
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Douglas D. Coolbaugh, et al

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL*		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA						
	AB						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		JP5-047859A	2/26/1993	JAPAN				

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

BS	S.G. Bombardier, et al. (1997) "Aluminum-Tungsten-Aluminum Sandwich for Semiconductor Chip Wirebond Pad", IBM Technical Disclosure Bulletin, Vol. 40, No. 6, page 131;
1	C.R. Fedorko, Jr., et al. (1984) "Packaging Substrate with Top Surface Metallurgy Adapted for Mixed Technology Device Bonding and Method", IBM Technical Disclosure Bulletin, Vol. 26, No. 12, page 6624;
	D. Chance, et al. (1993) "Thin Film Metallurgical Structure and Wire for Engineering Chance", IBM Technical Disclosure Bulletin, Vol. 36, No. 1, page 41;
	T.H. Chiles (1989) Abstract of Disclosure No. 30581 entitled "Use of a Composite Metal Pad for Wirebond connection to the Copper Core of a Metal Core Substrate Circuit Board" Kenneth Mason Publications, Ltd. England, No. 305 (1 page); and
↓	R. J. Bergeron, et al. (1992) Abstract of Disclosure No. 34237 entitled "Bond Pad Metallurgy for Wire Bonding", Kenneth Mason Publications, Ltd. England, No. 342 (1 page).

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DATE CONSIDERED

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